

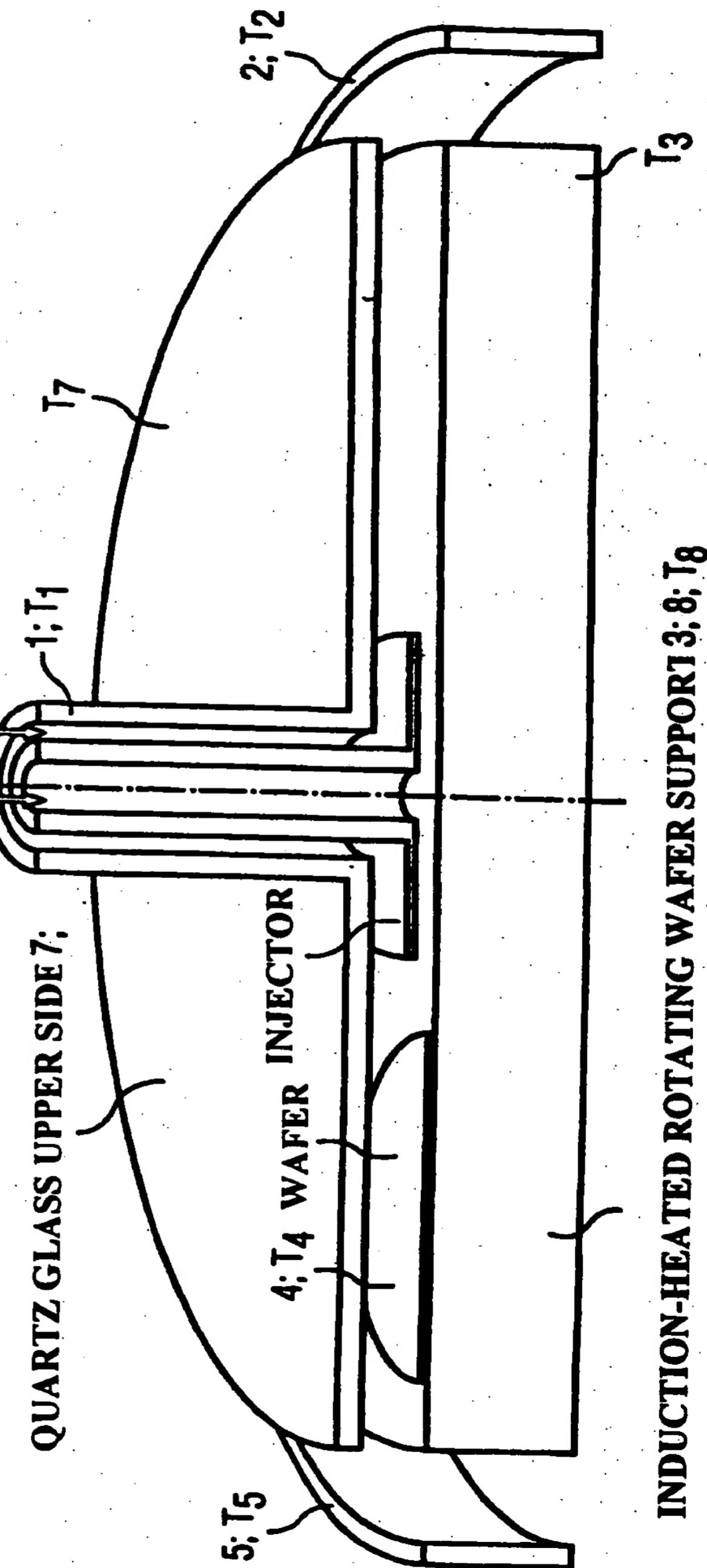


1/11

FIG 1



SECOND SUPPORT +
GROUP-V ELEMENTS
MAIN SUPPORT + GROUP III
ELEMENTS + DOPING SUBSTANCES



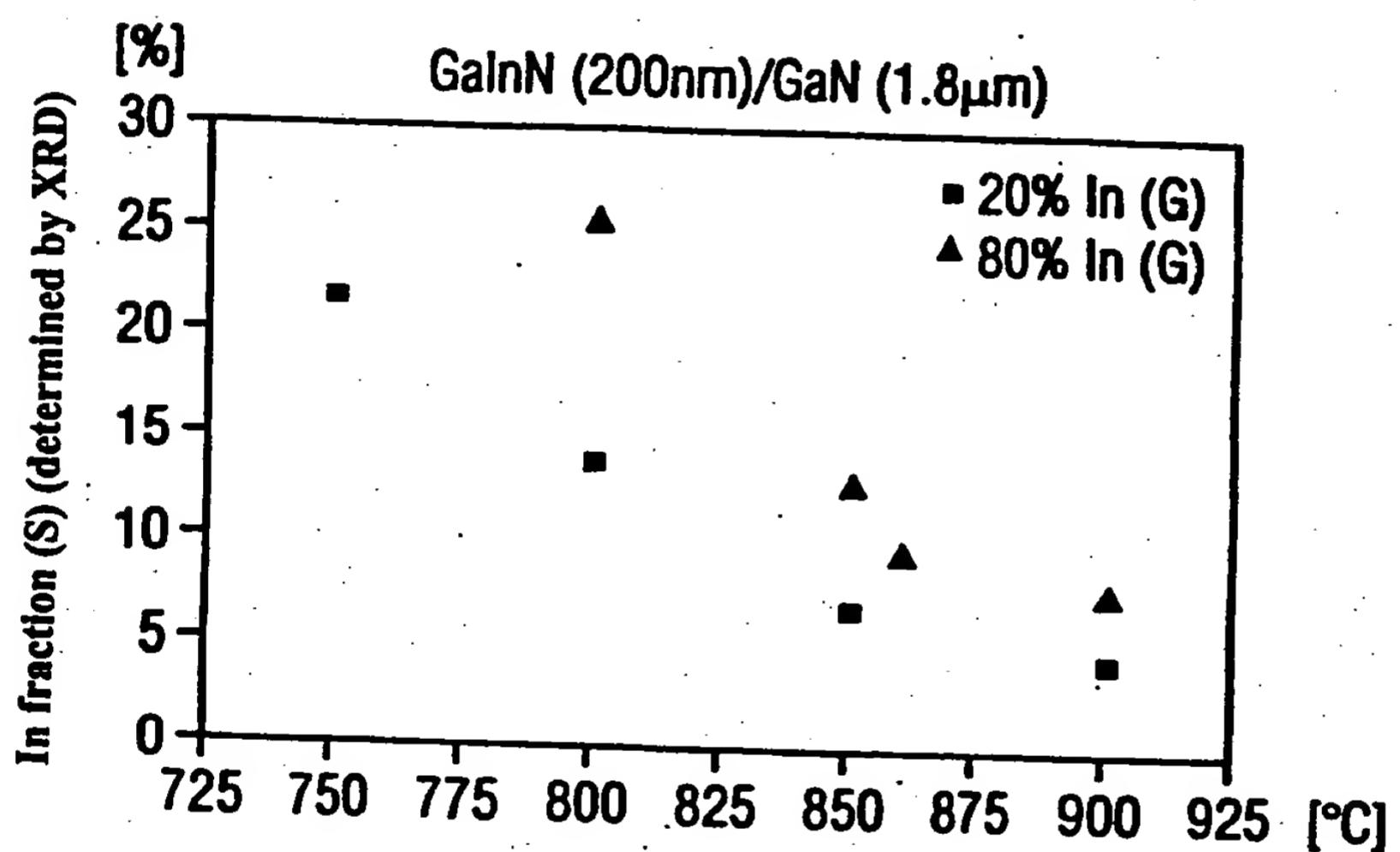
INDUCTION-HEATED ROTATING WAFER SUPPORT 3; 8; T8



2/11

FIG 2

In fraction as a function of the production temperature

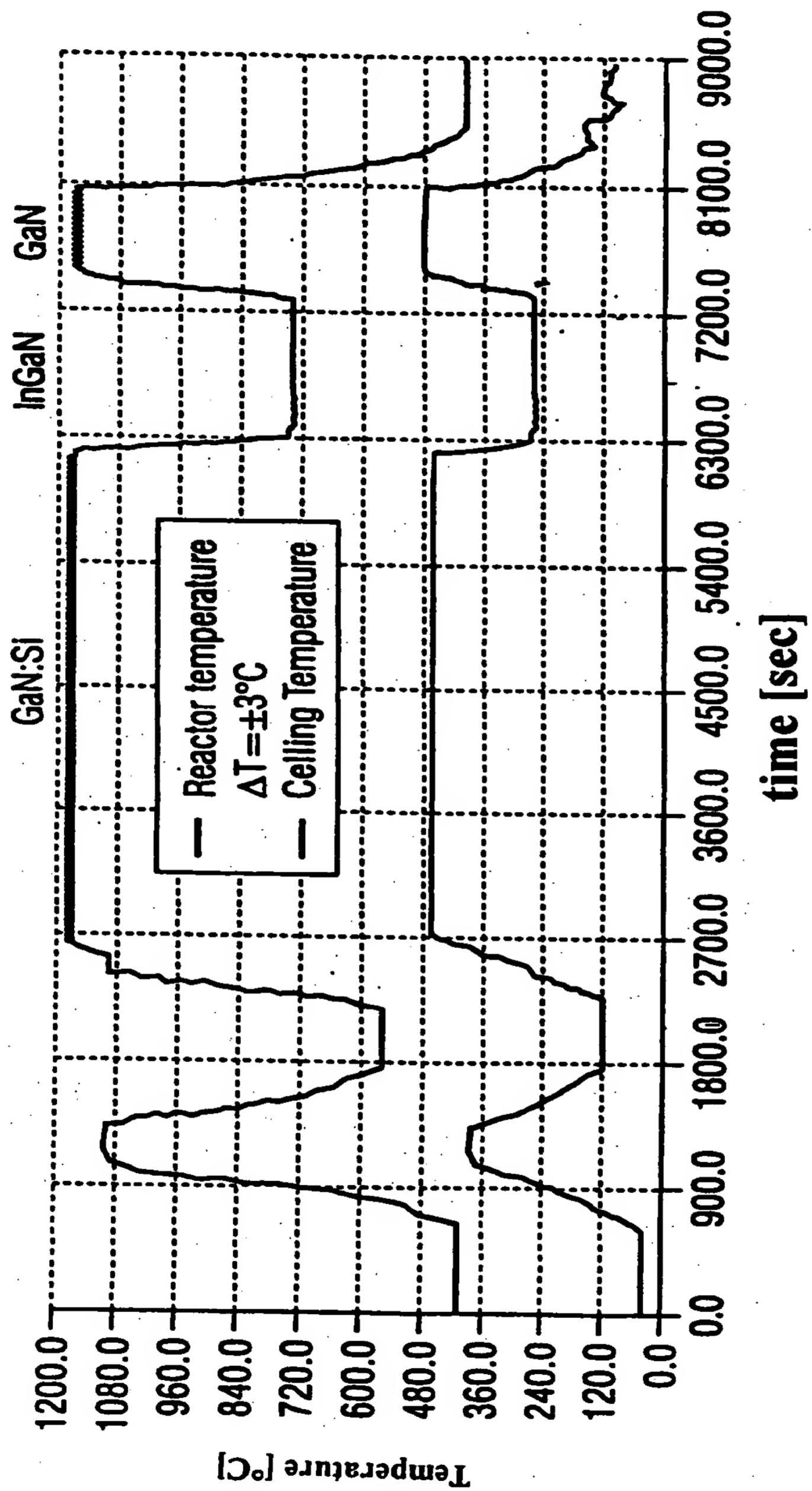




3/11

LOG data of the AIXTRON MOVPE system
InGaN/GaN DH structure

FIG 3



Replacement Sheet

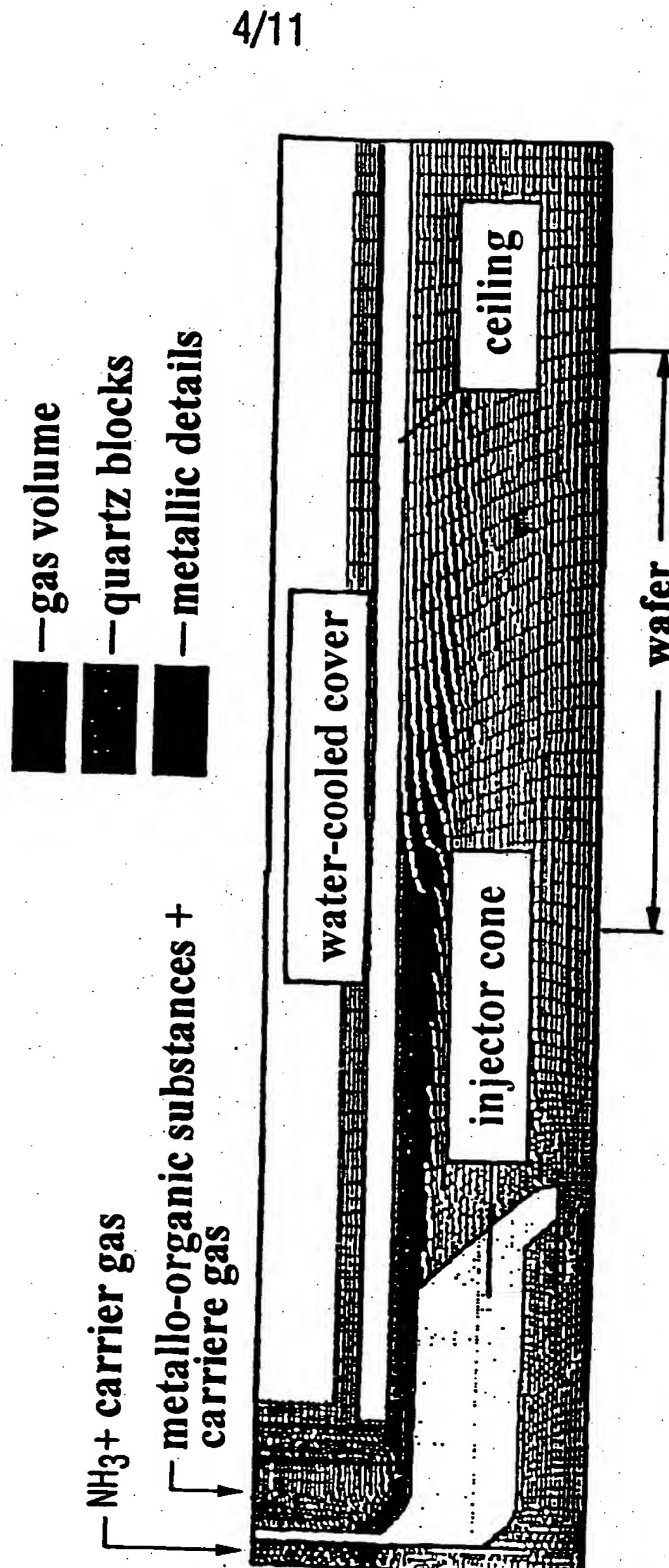
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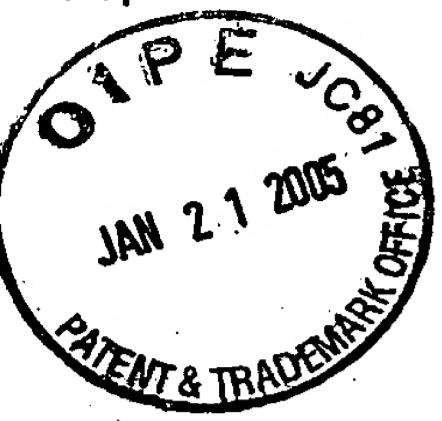


Mass Transfer Model

Schematic illustration the computing range and the finite volume lattice for analysing the mass transfer

FIG 3a





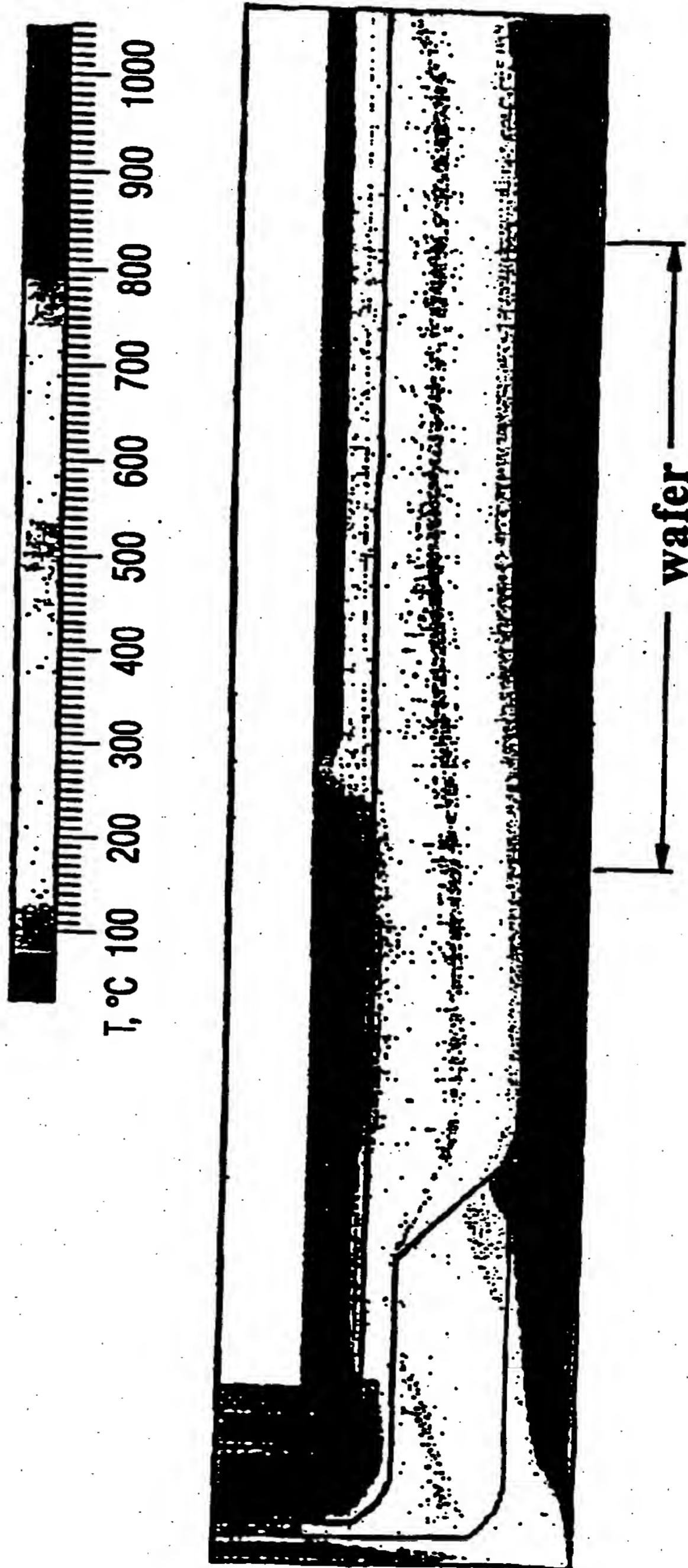
5/11

Temperature Distribution

The model explains:

- mixture and reaction of precursor flows
- grey diffuse radiation
- conjugated heat transmission

FIG 3b

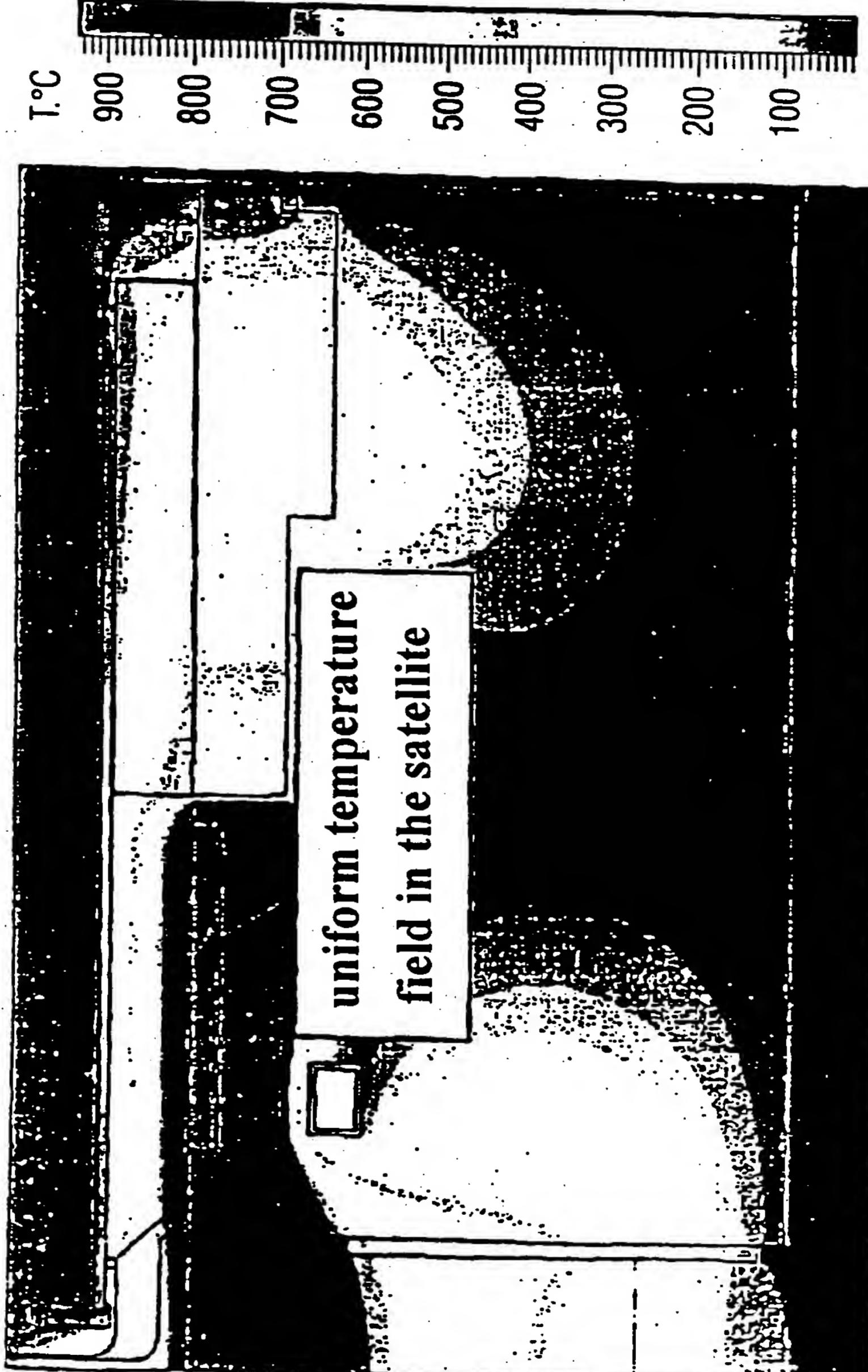




6/11

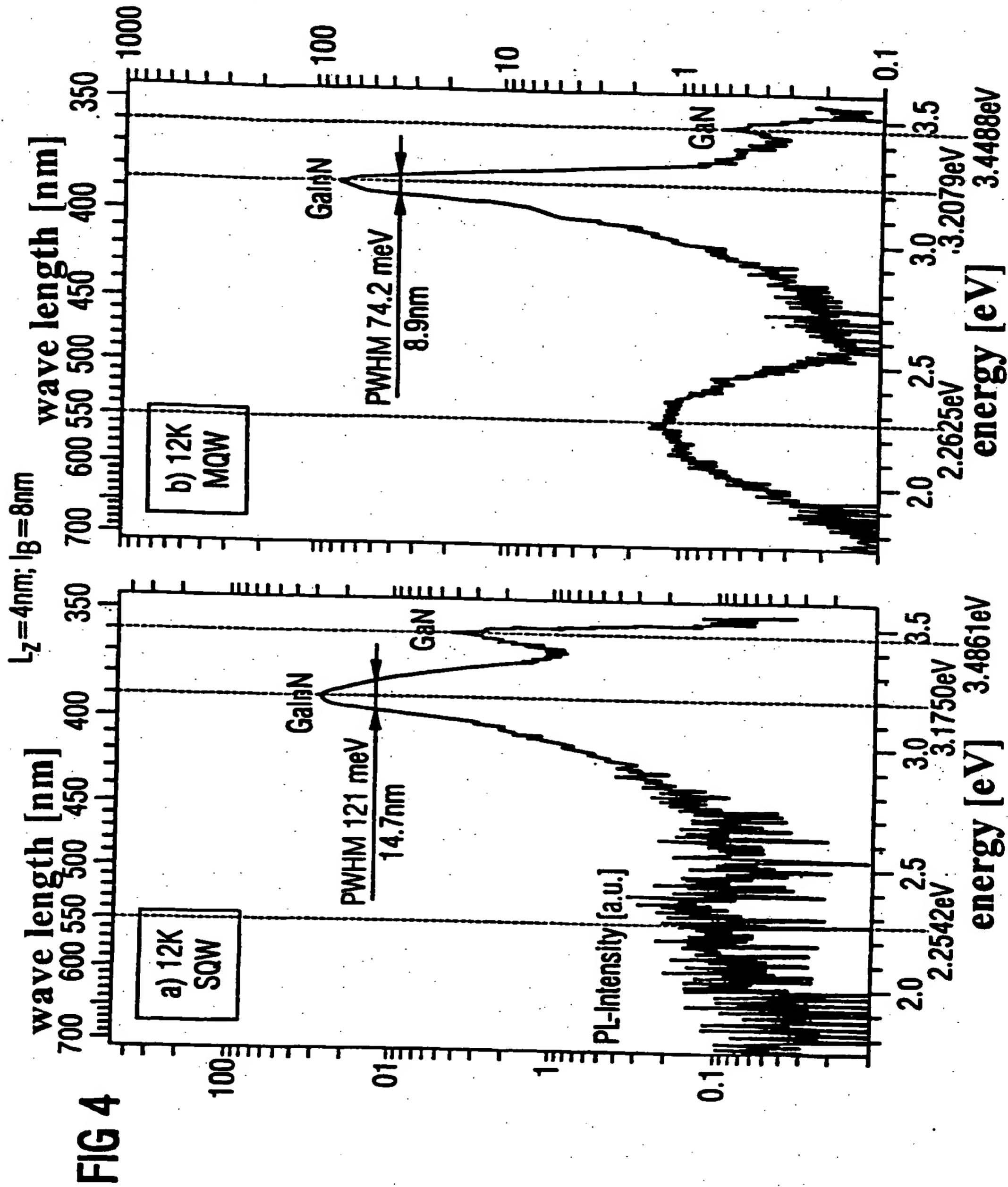
Detailed Thermal Model
Temperature Distribution
FIG 3C

Total output 14 KW; cooling-gas mixture 50%H₂+50%N₂





LT(12K)PL of SQW and MQW structures



Uniformity of InGaN production in a multiple-wafer reaction chamber

Production in ALX 2000HT, wafer size: 7 X 2"

Replacement Sheet



Application No. 09/873,041
Method and System for Semiconductor Crystal Production
With Temperature Management
Heukens et al.
SSJR File: 03345-P0017A

8/11

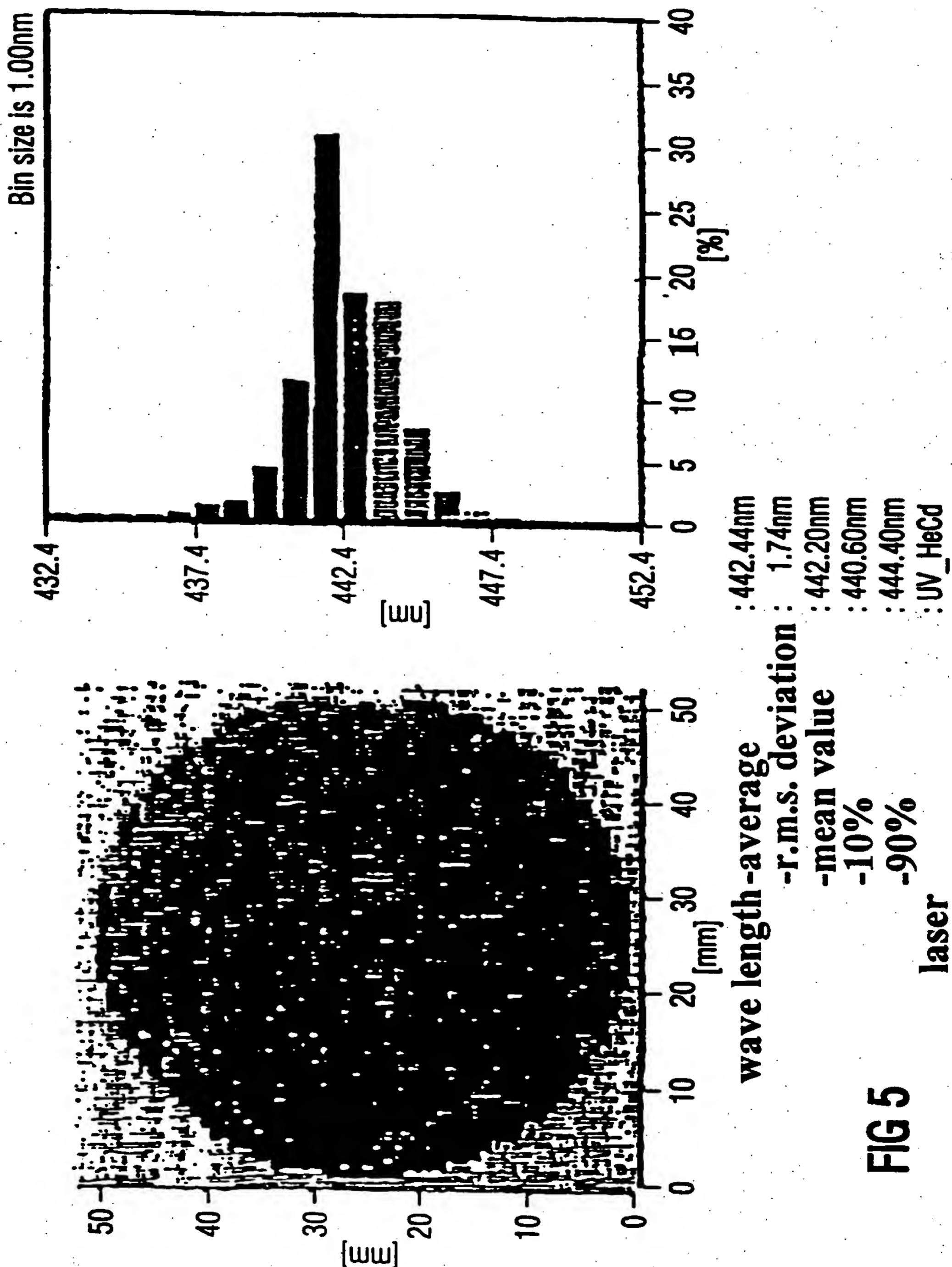


FIG 5

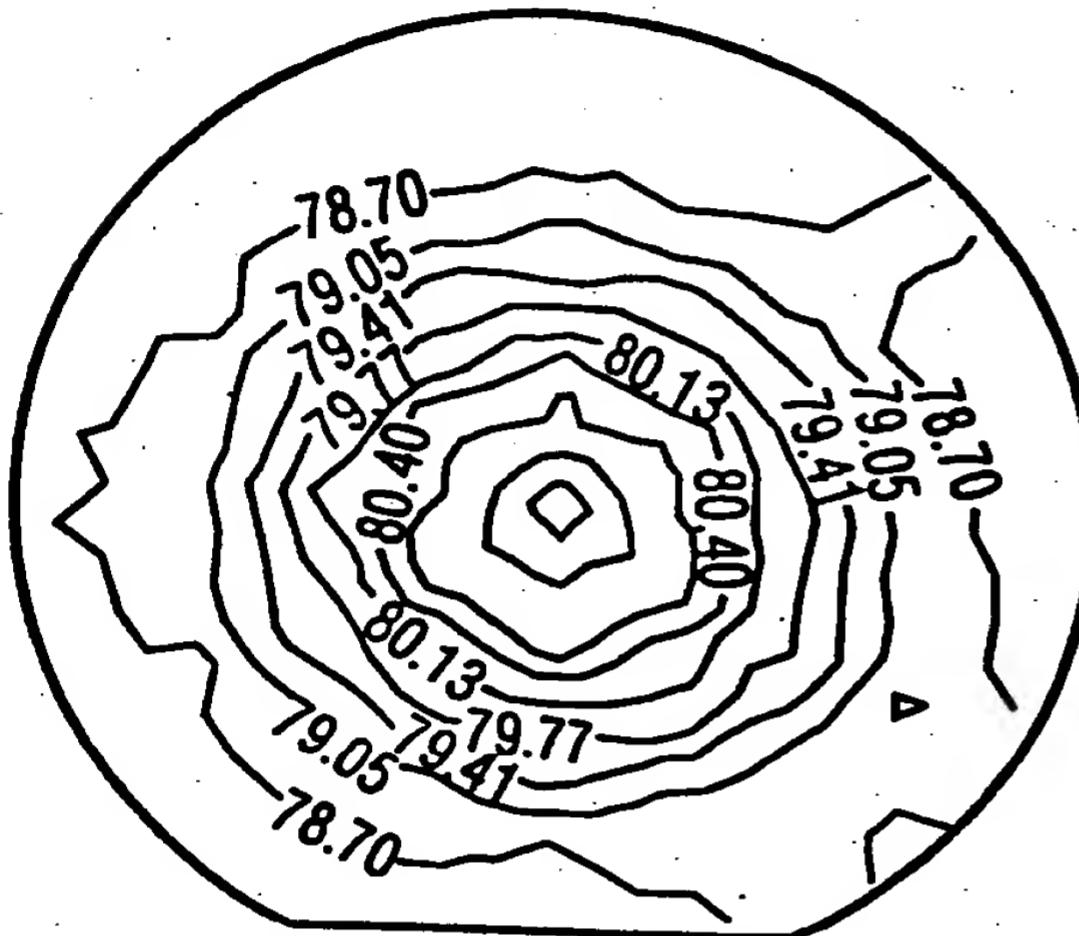
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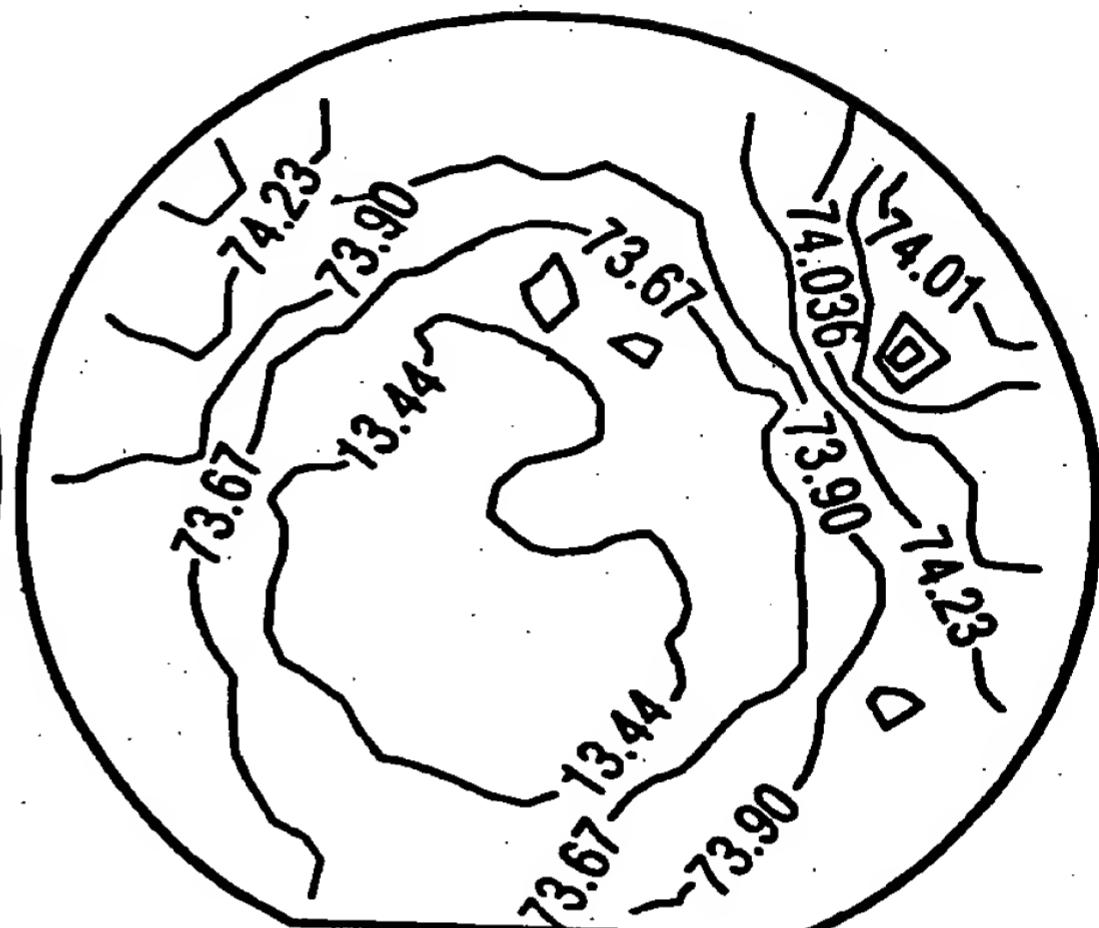
9/11

FIG 6

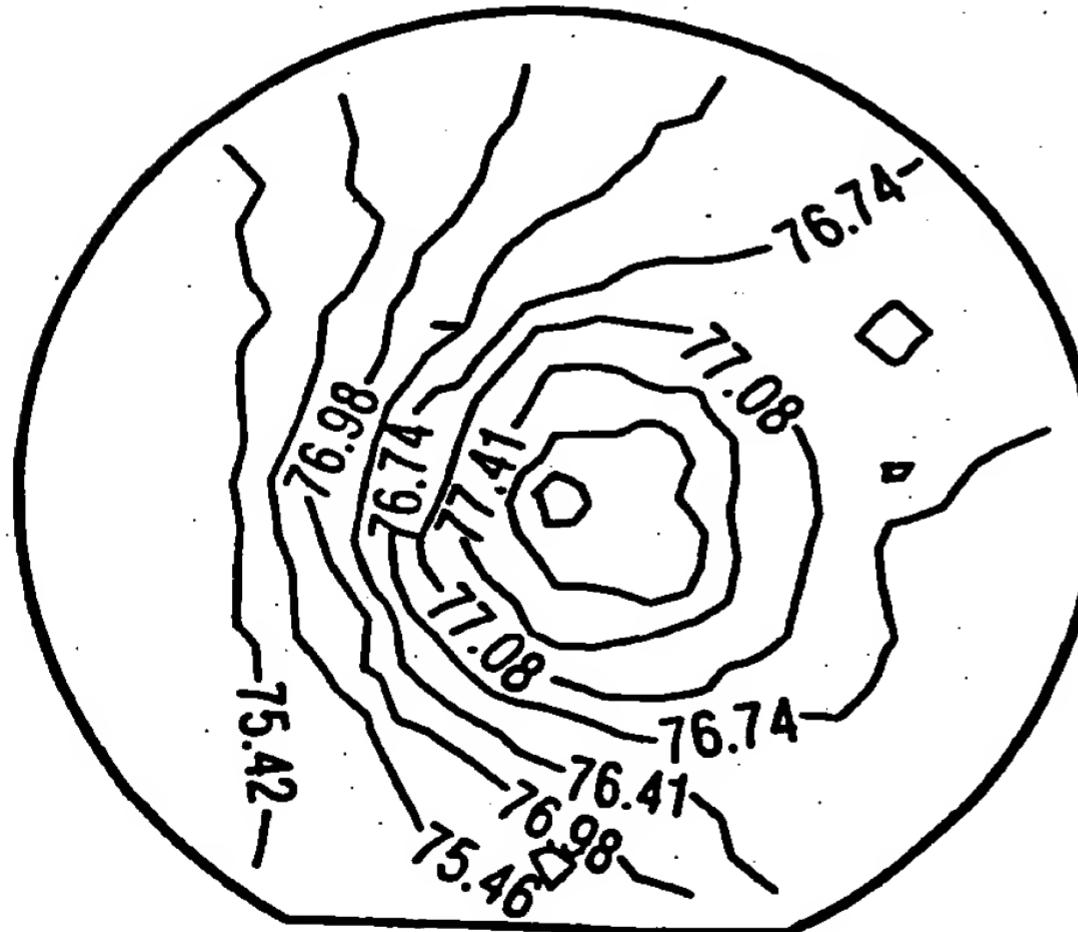
Wafer-to-wafer homogeneity of n-doped
GaN/InGaN-DHS



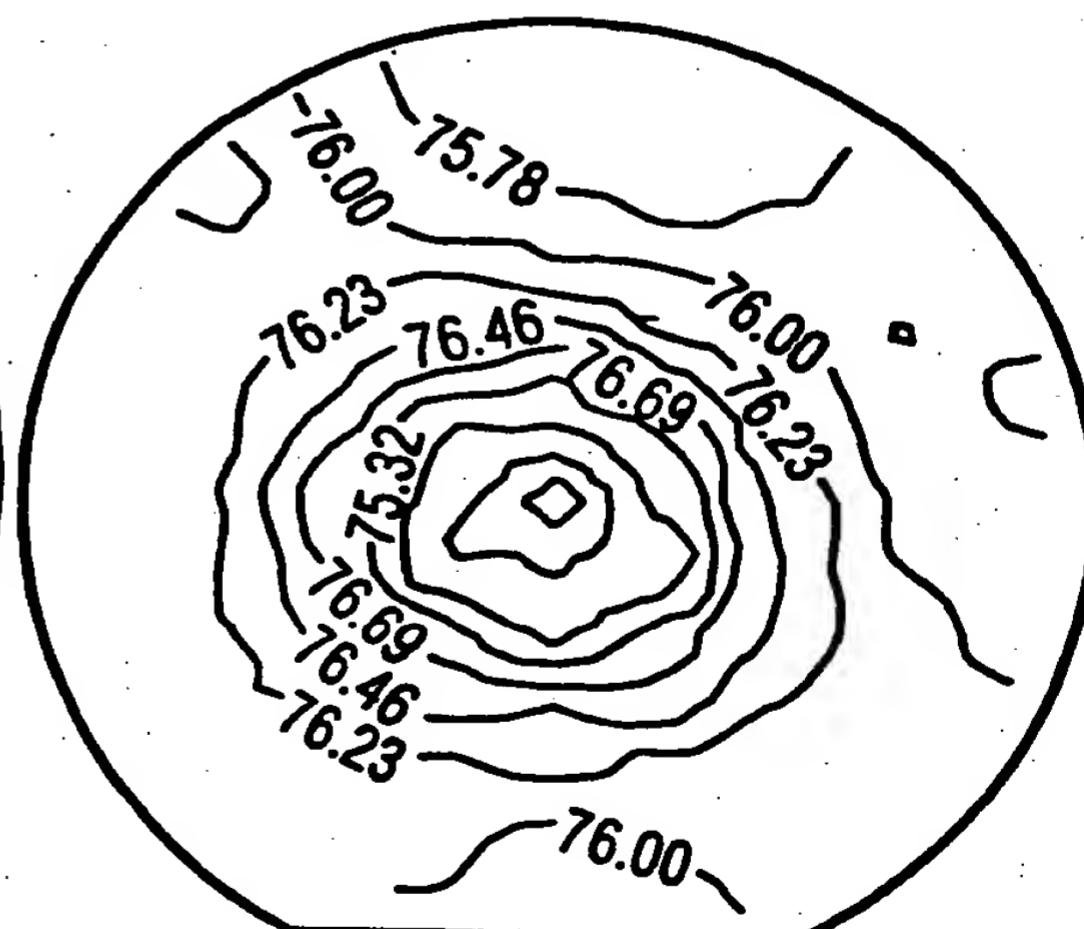
av. value: 79.2 ohm/sq
std. dev. 1.19%



av. value: 73.8 ohm/sq
std. dev. 0.61%

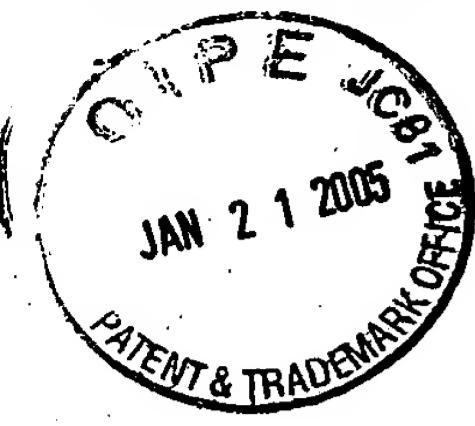


av. value: 76.4 ohm/sq
std. dev. 1.10%



av. value: 76.2 ohm/sq
std. dev. 0.68%

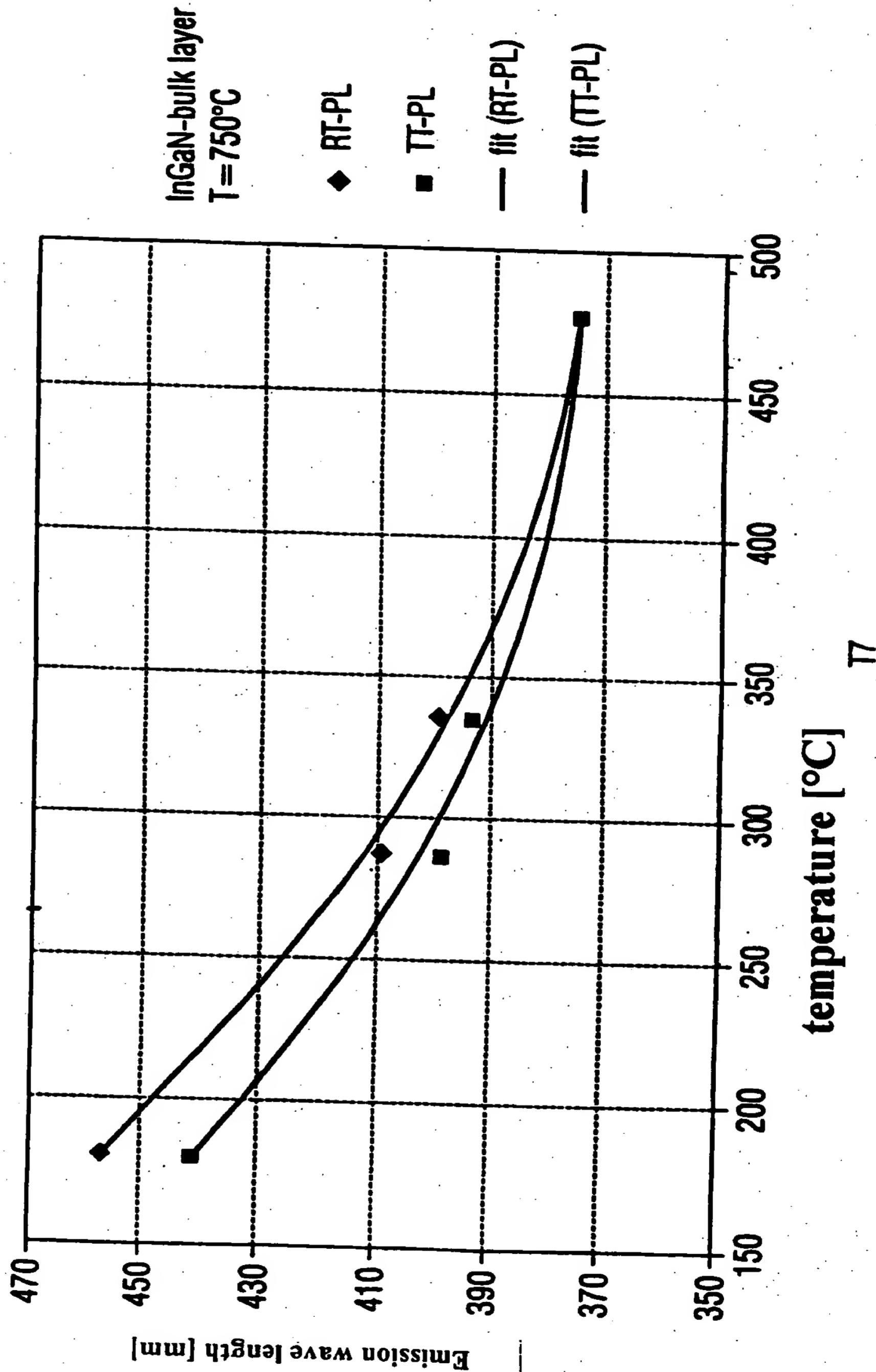
Wafer-to-wafer r.m.s. deviation: 2,7%



10/11

In incorporation as a function of the temperature
of the upper side of the reaction chamber

FIG 7



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Application No. 09/873,041
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SSJR File: 03345-P0017A

- reaction chamber underside T9
- reaction chamber injector T1
- reaction chamber ring T2
- reaction chamber upper side T7

FIG 8

11/11

